



### High Quality Product

Patented "Ultrasonic Bonding" technology is applied for the chip mounting. Omron's inlay is strong against bending stress and has a lower deficit rate.

### Inlay Class

EPCglobal compliant.

EPCglobal protocol Class 1 (96bits).

C1G2 (Generation 2) will be commercialized when the C1G2 chip is released.

### Thinness and Flexibility

Thickness of antenna is 9µm with tension of 7.5N at ø20mm iron stick.

These characteristics make inlay conversion easy.

### V740 Inlay General Specifications

<b>Size</b>	16 mm x 94 mm (0.63" x 3.70")
<b>Operating Frequency</b>	915 MHz
<b>Protocol</b>	EPCglobal Protocol Class 1 (96 bits)
<b>Memory Size</b>	128 bits EEPROM (User memory area: 96 bits)
<b>Data Retention</b>	Time 10 years
<b>Data Write Endurance</b>	10,000 cycles
<b>Operating Temperature</b>	-20°C to 55°C (-4°F to 131°F) (no icing, no condensation)
<b>Storage Temperature</b>	-20°C to 55°C (-4°F to 131°F) (no icing, no condensation)
<b>Storage Humidity</b>	60% RH max.
<b>Heat Resistance</b>	No communication error after 250 hours at 85°C (185°F)
<b>Cold Resistance</b>	No communication error after 250 hours at -30°C (-22°F)
<b>Thermal Shock Resistance</b>	No communication error after 100 cycles between 85°C (185°F) and -30°C (22°F) holding 30 minutes at each temperature.
<b>Vibration Resistance</b>	Destruction: 10 to 2,000 Hz, 1.5 mm (0.06 in) double amplitude at 150 m/s <sup>2</sup> (492.1 ft/s <sup>2</sup> ) in X, Y, and Z directions 10 times each for 11 minutes
<b>Shock Resistance</b>	Destruction: 500 m/s <sup>2</sup> (1640 ft/s <sup>2</sup> ) three times each in X, Y, and Z directions

This product is only sold in the U.S.A. at present.

